

Shuo Huang

List of Publications by Year in descending order

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Version: 2024-02-01

15
papers

471
citations

840585

11
h-index

1199470

12
g-index

15
all docs

15
docs citations

15
times ranked

583
citing authors

#	ARTICLE	IF	CITATIONS
1	A general memristor-based partial differential equation solver. Nature Electronics, 2018, 1, 411-420.	13.1	183
2	Plasma etching of high aspect ratio features in SiO ₂ using Ar/C ₄ F ₈ /O ₂ mixtures: A computational investigation. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 2019, 37, .	0.9	64
3	Calculated cross sections for electron collisions with NF ₃ , NF ₂ and NF with applications to remote plasma sources. Plasma Sources Science and Technology, 2017, 26, 065010.	1.3	45
4	Pattern dependent profile distortion during plasma etching of high aspect ratio features in SiO ₂ . Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 2020, 38, .	0.9	30
5	A particle-in-cell/Monte Carlo simulation of a capacitively coupled chlorine discharge. Plasma Sources Science and Technology, 2013, 22, 055020.	1.3	27
6	Insights to scaling remote plasma sources sustained in NF ₃ mixtures. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 2017, 35, 031302.	0.9	23
7	Highly selective Si ₃ N ₄ /SiO ₂ etching using an NF ₃ /N ₂ /O ₂ /H ₂ remote plasma. I. Plasma source and critical fluxes. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 2020, 38, 023007.	0.9	22
8	A current driven capacitively coupled chlorine discharge. Plasma Sources Science and Technology, 2014, 23, 025015.	1.3	21
9	Downstream etching of silicon nitride using continuous-wave and pulsed remote plasma sources sustained in Ar/NF ₃ /O ₂ mixtures. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 2018, 36, .	0.9	17
10	Highly selective Si ₃ N ₄ /SiO ₂ etching using an NF ₃ /N ₂ /O ₂ /H ₂ remote plasma. II. Surface reaction mechanism. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 2020, 38, .	0.9	17
11	Dual-frequency capacitively coupled chlorine discharge. Plasma Sources Science and Technology, 2015, 24, 015003.	1.3	11
12	Ion Energy and Angular Distributions in a Dual-Frequency Capcitively Coupled Chlorine Discharge. IEEE Transactions on Plasma Science, 2014, 42, 2854-2855.	0.6	7
13	Microneedle Penetrating Array with Axon-Sized Dimensions for Cuff-less Peripheral Nerve Interfacing. , 2019, , .		4
14	Optimizing remote plasma sources for selective etching. , 2016, , .		0
15	Contact Edge Roughness In The Etching Of High Aspect Ratio Contacts In SiO ₂ . , 2017, , .		0